



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: G0005-01 DATE: May 10, 2000
 Product Affected: All Plastic Packages
 Manufacturing Location Affected: All
 Date Effective: August 10, 2000

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark
- Date Code
- Other

Contact: PS Tow
 Title: Director, Corporate Quality & Reliability Attachment: Yes No
 Phone #: (408) 492-8206
 Fax #: (408) 727-2328 Samples:
 E-mail: pstow@idt.com

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
 - Wafer Fabrication Process
 - Assembly Process
 - Equipment
 - Material
 - Testing
 - Manufacturing Site
 - Data Sheet
 - Other
- IDT plans to introduce LASER TOP MARK as replacement to INK TOP MARK for all Plastic Packages. Initial conversion is for 300 mils SOJ, 150 mils SSOP and 300 mils SOIC packages. Additional packages will be converted in future on the as needed basis.
 During the transition period, shipment to customer will contain either INK or Laser Top mark only. There will be no mixing of ink and laser mark in one shipment.

RELIABILITY/QUALIFICATION SUMMARY: Not Applicable.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ *Approval for shipments prior to effective date.*
 Name/Date: _____ E-Mail Address: _____
 Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____